

AMENDMENTS TO THE CLAIMS

Claim 1 (Currently Amended): An enameled wire comprising
an ~~electrical~~ electrically conductive wire and
a coating layer ~~formed of~~ surrounding the wire, wherein
the coating layer comprises
a high molecular compound, and
an inorganic filler material in the form of fine flat particles aligned parallel to
the surface of the wire and uniformly dispersed in ~~said~~ the high molecular compound.

Claim 2 (Currently Amended): An enameled wire as claimed in claim 1, wherein ~~said~~
the inorganic filler material is a clay compound having a layer structure.

Claim 3 (Currently Amended): An enameled wire as claimed in claim 1, wherein ~~said~~
the inorganic filler material is boron nitride.

Claim 4 (Currently Amended): An enameled wire as claimed in claim 2, wherein ~~said~~
the clay compound having a layer structure includes at least one mineral selected from a
~~mineral~~ the group consisting of smectites, micas and vermiculites.

Claim 5 (Currently Amended): An enameled wire as claimed in claim 4, wherein a
metal cation existing between adjacent layers of ~~said~~ the clay compound is substituted by a
quaternary ammonium salt.

Claim 6 (Currently Amended): An enameled wire as claimed in claim 1, wherein ~~said~~ the high molecular compound is one of polyvinyl formal, polyester, polyester imide and polyamide imide.

Claim 7 (Currently Amended): An enameled wire comprising
an ~~electrical~~ electrically conductive ~~wire, wire;~~
a first coating layer surrounding ~~said electric conductive~~ the wire, ~~said where the~~ first
coating ~~being formed of~~ layer comprises
a high molecular compound ~~of comprising~~ polyester imide resin ~~solution , and~~
an inorganic filler material in the form of fine flat particles aligned parallel to
the surface of the wire and uniformly dispersed in ~~said the~~ high molecular ~~compound,~~
compound; and
a second coating ~~of layer comprising~~ polyamide imide ~~formed on said~~ the first coating
layer.

Claim 8 (Currently Amended): An enameled wire as claimed in claim 7, wherein ~~said~~
the second coating ~~of polyamide imide is mixed with an~~ layer comprises a dispersed
inorganic filler material in the form of fine flat particles ~~dispersed therein.~~

Claim 9 (Currently Amended): An enameled wire comprising
an electrically conductive ~~wire~~, wire;
a first coating ~~provided layer~~ on said ~~electrically conductive~~ the wire, said where the
first coating ~~being formed of~~ layer comprises a polyester imide ~~resin~~, resin; and
a second coating layer ~~formed on said~~ the first coating layer, said where the second
coating layer ~~being formed of~~ comprises
polyamide imide ~~mixed with~~ , and
an inorganic filler material in the form of fine flat particles aligned parallel to
the surface of the wire and uniformly dispersed therein in the polyamide imide of the second
coating layer.

Claim 10 (Currently Amended): An enameled wire as claimed in any one of claims 1
to 9 6, wherein said
the inorganic filler material ~~is in the form of fine flat particles having~~ has an average
particle size of 1 μ m or less; and ~~a ratio is 0.5 ~ 15~~
the coating layer comprises 0.5 to 15 weight parts of said the inorganic filler material
relative to 100 weight parts of said the high molecular compound.

Claim 11 (New): An enameled wire as claimed in claim 7 or 8, wherein
the inorganic filler material has an average particle size of 1 μ m or less; and
the first coating layer comprises 0.5 to 15 weight parts of the inorganic filler material
relative to 100 weight parts of the polyamide imide resin of the first coating layer.

Claim 12 (New): An enameled wire as claimed in claim 9, wherein
the inorganic filler material has an average particle size of 1 μm or less; and
the second coating layer comprises 0.5 to 15 weight parts of the inorganic filler
material relative to 100 weight parts of the polyamide imide of the second coating layer.

Claim 13 (New): A method of making an enameled wire, the method comprising
coating on an electrically conductive wire a mixture containing a high molecular
compound and an inorganic filler material; and
producing the wire of claim 1.